SDI Review Form 1.6

Journal Name:	**Journal of Engineering Research and Reports**
Manuscript Number:	**Ms_JERR_66645**
Title of the Manuscript:	**Addressing Delamination through Advanced Semiconductor Die Design**
Type of the Article	**Original Research Article**

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty'**, provided the manuscript is scientifically robust and technically sound.
To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(http://www.sciencedomain.org/journal/10/editorial-policy)

PART 1: Review Comments

	Reviewer's comment	**Author's comment** *(if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)*
Compulsory REVISION comments	interesting paper, as it presented a new semiconductor mold design with metallized sidewall to establish a robust interface with the epoxy mold fixing material. Good application of epoxy putty	Thank you.
Minor REVISION comments	interesting paper as it provides practical application of epoxy putty	Thank you.
Optional/General comments	good quality paper	Thank you very much.

PART 2:

	Reviewer's comment	**Author's comment** *(if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)*
Are there ethical issues in this manuscript?	*(If yes, Kindly please write down the ethical issues here in details)*	